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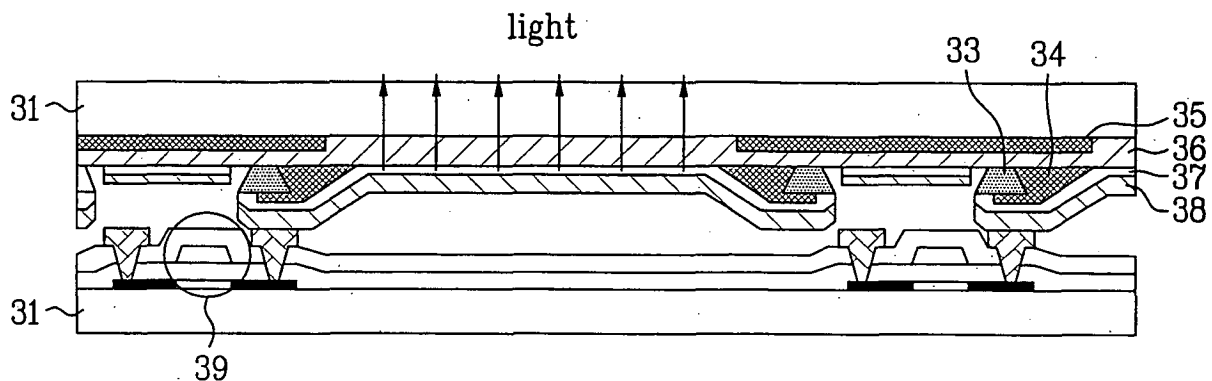
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(54) **Organic electroluminescence display and method for manufacturing the same**

(57) An adhesive type organic EL display, and a method for manufacturing the same are disclosed. The organic EL display comprises a first substrate having a thin transistor formed thereon, and a second substrate having an organic EL element formed thereon. The or-

ganic EL display further comprises at least two partition walls formed in a non-light emitting region of the second substrate, an insulation layer formed to cover a portion of each partition wall, and a second electrode, which is formed on the partition walls, and electrically connected to the thin transistor of the first substrate.

FIG. 2



EP 1 667 245 A2

Description

[0001] This application claims the benefit of Korean Patent Application No. 10-2004-0100360, filed on December 2, 2004, which is hereby incorporated by reference as if fully set forth herein.

BACKGROUND OF THE INVENTION

Field of the Invention

[0002] The present invention relates to an organic electroluminescence (EL) display, and more particularly, to an adhesive type organic EL display, and a method for manufacturing the same.

Discussion of the Related Art

[0003] Generally, an adhesive type organic EL display comprises a lower panel having a pixel switching element and a pixel driving element formed thereon, and an upper panel having organic materials stacked thereon, in which the lower board is electrically connected with the upper board by bonding the upper and lower panels, thereby embodying the display.

[0004] A method for manufacturing a conventional adhesive type organic EL display will be described as follows.

[0005] FIG. 1 shows a cross-sectional view illustrating a conventional adhesive type organic EL display.

[0006] In FIG. 1, the display comprises a lower panel having a thin transistor formed thereon, and an upper panel having an organic EL element formed thereon.

[0007] Referring to FIG. 1, the lower panel of the organic EL display is manufactured by the following process.

[0008] First, a semiconductor layer 2 is formed using a polycrystalline silicon on a transparent substrate 1, and is removed via patterning except for a region where the thin transistor will be formed.

[0009] Next, after sequentially forming a gate insulation layer 3, and a conductive layer for a gate electrode over the entire surface of the substrate 1, the conductive layer is patterned to form a gate electrode 4.

[0010] Then, impurity ions such as phosphorus (P) are implanted to the semiconductor layer 2 using the gate electrode 4 as a mask, and then source/drain regions are formed by annealing the substrate, thereby forming an N-MOS thin transistor.

[0011] At this time, portions of the semiconductor layer 2 where the impurity ions are not implanted become channel regions.

[0012] Next, an interlayer insulation layer 5 is formed over the entire surface of the substrate comprising the above components, and the interlayer insulation layer 5 and the gate insulation layer 3 are selectively removed such that the source/drain regions of the N-MOS transistor are exposed.

[0013] Then, an electrode line 6 is formed on the substrate such that the electrode line 6 is electrically connected with the source/drain regions, respectively, thereby completing manufacture of the lower panel.

5 [0014] Next, referring to FIG. 1, the upper panel of the organic EL display is manufactured by the following process.

[0015] First, an anode 8 composed of a transparent conductive material having a high work function such as ITO or IZO is formed on a transparent substrate 7.

[0016] Then, an insulation layer 9 is formed on some portion of the anode 8 using an insulation material such as polyimide, and a partition wall 10 is formed on the insulation layer 9.

10 [0017] Next, an island-shaped spacer 11 is formed in a pixel region using another insulation material.

[0018] Then, a cathode 13 composed of a conductive material having a low work function such as aluminum is deposited on an electron implantation layer, thereby completing manufacture of the upper panel.

[0019] The upper and lower panels manufactured as described above are attached to each other.

[0020] At this time, the upper and lower panels are electrically connected by contacting the cathode 13 formed on the spacer 11 of the upper panel with the electrode line 6 of the lower panel.

20 [0021] However, the adhesive type organic EL display manufactured as described above has the following problems.

[0022] In general, since the spacer has a higher profile than that of the partition wall, and must be formed to have a gentle side angle, it is difficult to form the spacer.

[0023] In addition, when forming the organic material using a shadow mask, the spacer is likely to be collapsed or damaged by the shadow mask.

25 [0024] Furthermore, since the spacer is formed in a light emitting region, an aperture ratio is reduced.

SUMMARY OF THE INVENTION

30 [0025] Accordingly, the present invention is directed to an adhesive type organic EL display, and a method for manufacturing the same that substantially obviates one or more problems due to limitations and disadvantages of the related art.

[0026] An object of the present invention is to provide an adhesive type organic EL display, which does not comprise a spacer, and a method for manufacturing the same.

35 [0027] Another object of the present invention is to provide an adhesive type organic EL display, and a method for manufacturing the same, which can simplify a process, enhance reliability of the product, and has a high optical efficiency.

40 [0028] Additional advantages, objects, and features of the invention will be set forth in part in the description which follows and in part will become apparent to those having ordinary skill in the art upon examination of the

following or may be learned from practice of the invention. The objectives and other advantages of the invention may be realized and attained by the structure particularly pointed out in the written description and claims hereof as well as the appended drawings.

[0029] To achieve these objects and other advantages and in accordance with the purpose of the invention, as embodied and broadly described herein, an adhesive type organic EL display comprising a first substrate having a thin transistor formed thereon, and a second substrate having an organic EL element formed thereon, the thin transistor of the first substrate being electrically connected with the organic EL element of the second substrate further comprises: at least two partition walls formed in a non-light emitting region of the second substrate; an insulation layer formed to cover a portion of each partition wall; and a second electrode formed on the partition walls, and electrically connected to the thin transistor of the first substrate.

[0030] Each of the partition walls may have a structure of substrate/assistant electrode/first electrode or a structure of substrate/first electrode/assistant electrode stacked therebelow.

[0031] The non-light emitting region may have a structure of substrate/assistant electrode/first electrode/organic light emitting layer/second layer or a structure of substrate/first electrode/second electrode stacked between the partition walls.

[0032] The insulation layer covering the portion of one partition wall may be symmetrical to the insulation layer covering the portion of the other partition wall adjacent to the one partition wall.

[0033] In another aspect of the present invention, an organic EL display comprising a first substrate having a thin transistor formed thereon, and a second substrate having an organic EL element formed thereon, further comprises: a light emitting region, and a non-light emitting region provided to the second substrate; an assistant electrode formed on the second substrate of the non-light emitting region; a first electrode formed over an entire surface of the second substrate including the assistant electrode; at least two partition walls formed on the first electrode of the non-light emitting region; an insulation layer to cover a portion of each partition wall; a light emitting layer formed on the first electrode of the light emitting region; and a second electrode formed over the entire surface of the second substrate including the light emitting layer, and electrically connected to the thin transistor of the first substrate.

[0034] In yet another aspect of the present invention, an organic EL display comprising a first substrate having a thin transistor formed thereon, and a second substrate having an organic EL element formed thereon further comprises: a light emitting region, and a non-light emitting region provided to the second substrate; a first electrode formed on the second substrate; an assistant electrode formed on the first electrode of the non-light emitting region; partition walls formed on the assistant electrode;

an insulation layer to cover a portion of each partition wall; a light emitting layer formed on the first electrode of the light emitting region; and a second electrode formed over an entire surface of the second substrate including the light emitting layer, and electrically connected to the thin transistor of the first substrate.

[0035] In another yet aspect of the present invention, a method for manufacturing an organic EL display comprises the steps of: forming an assistant electrode on a non-light emitting region of a second substrate; forming a first electrode over an entire surface of the second substrate including an upper or lower portion of the assistant electrode; forming partition walls on a region where the assistant electrode is formed; forming an insulation layer to cover a portion of each partition wall; forming a light emitting layer on the first electrode of the light emitting region; and forming a second electrode over the entire surface of the second substrate including the light emitting layer; and electrically connecting the second electrode with a thin transistor of a first substrate.

[0036] It is to be understood that both the foregoing general description and the following detailed description of the present invention are exemplary and explanatory and are intended to provide further explanation of the invention as claimed.

BRIEF DESCRIPTION OF THE DRAWINGS

[0037] The accompanying drawings, which are included to provide a further understanding of the invention and are incorporated in and constitute a part of this application, illustrate embodiment(s) of the invention and together with the description serve to explain the principle of the invention. In the drawings:

[0038] FIG. 1 is a cross-sectional view illustrating a conventional adhesive type organic EL display;

[0039] FIG. 2 is a cross-sectional view illustrating an adhesive type organic EL display in accordance with a first embodiment of the present invention;

[0040] FIG. 3 is a cross-sectional view illustrating an adhesive type organic EL display in accordance with a second embodiment of the present invention;

[0041] FIGs. 4A to 4E are cross-sectional views for illustrating steps of a method for manufacturing an adhesive type organic EL display in accordance with the first embodiment;

[0042] FIGs. 5A to 5D are cross-sectional views for illustrating steps of a method for manufacturing an adhesive type organic EL display in accordance with the second embodiment; and

[0043] FIGs. 6A and 6B are views illustrating the shapes of partition walls of the adhesive type organic EL display in accordance with the present invention.

DETAILED DESCRIPTION OF THE INVENTION

[0044] Reference will now be made in detail to the preferred embodiments of the present invention, examples

of which are illustrated in the accompanying drawings. Wherever possible, the same reference numbers will be used throughout the drawings to refer to the same or like parts.

[0045] FIG. 2 is a cross-sectional view illustrating an adhesive type organic EL display in accordance with a first embodiment of the present invention.

[0046] As shown in Fig. 2, the organic EL display of the first embodiment comprises a first substrate 31 having an a-Si thin transistor 39 formed thereon, and a second substrate 32 which has an organic EL element formed thereon, and is bonded to the first substrate 31.

[0047] An electrode of the thin transistor of the first substrate 31 is electrically connected with an electrode of the organic EL element of the second substrate 32.

[0048] The second substrate 32 has an assistant electrode 35, a first electrode 36 acting as an anode, at least two partition walls 33, an insulation layer 34, an organic light emitting layer 37, and a second electrode 38 acting as a cathode, formed thereon.

[0049] The at least two partition walls 33 are formed in a non-light emitting region of the second substrate 32, in which the first electrode 36, and the assistant electrode 35 are formed below each partition wall 33.

[0050] The insulation layer 34 is formed to cover a portion of each partition wall 33.

[0051] Here, the insulation layer 34 covering the portion of one partition wall 33 is symmetrical to the insulation layer covering the portion of the other partition wall 33 adjacent to the one partition wall 33.

[0052] In other words, the insulation layer 34 is formed on opposite sides of adjacent partition walls 33 in which the opposite sides do not face each other, and the organic light emitting layer 37 is formed between the sides of the adjacent partition walls 33 in which the sides face each other.

[0053] A method for manufacturing the organic EL display of the first embodiment will be described as follows.

[0054] FIGs. 4A to 4E are cross-sectional views for illustrating steps of the method for manufacturing an adhesive type organic EL display in accordance with the first embodiment.

[0055] First, as shown in FIG. 4A, an assistant electrode 35 is formed on a non-light emitting region of a second substrate 32.

[0056] Here, the assistant electrode 35 is composed of a conductive material, and preferably, of Al, Mo, an AnNd alloy, Cr, Cu, and the like.

[0057] Next, as shown in FIG. 4B, a first electrode 36 is formed over the entire surface of the second substrate 32 including the assistant electrode 35.

[0058] The first electrode 36 acts as an anode, and is preferably composed of at least one of ITO and IZO.

[0059] Then, as shown in FIG. 4C, at least two partition walls 33 are formed on the first electrode 36 where the assistant electrode 35 is formed.

[0060] Here, as shown in FIG. 6A, each of the partition walls 33 preferably is a structure wherein a lower surface

thereof is narrower than an upper surface thereof to be formed with the second electrode 38.

[0061] In addition, as shown in FIG. 6B, each of the partition walls 33 may comprise a first section 50, which has a lower surface thereof wider than an upper surface thereof to be formed with the second electrode 38, and a second section 51, which is formed on the upper surface of the first section 50 and wider than the lower surface of the first section 50.

[0062] Then, as shown in FIG. 4D, an insulation layer 34 is formed to cover a portion of each partition wall 33.

[0063] Here, the insulation layer 34 is formed on opposite sides of adjacent partition walls 33 in which the opposite sides do not face each other.

[0064] The insulation layer 34 can be composed of an organic material or an inorganic material, and is preferably composed of a polymeric material.

[0065] In particular, the insulation layer 34 advantageously comprises at least one of photosensitive polyimide, polyacryl, and novolac-based organic insulation layers.

[0066] In addition, as shown in FIG. 4E, an organic light emitting layer 37 is formed on the first electrode 36 of the light emitting region, and a second electrode 38 acting as a cathode is formed over the entire surface of the second substrate 32 including the organic light emitting layer 37.

[0067] Then, the first substrate 31 having the thin transistor is attached to the second substrate 32 having the organic EL element such that the second electrode 38 is electrically connected with the thin transistor of the first substrate 31, thereby completing the manufacture of the organic EL display.

[0068] At this time, the first substrate 31 is attached to the second substrate 32 using a sealant such that the organic EL display has an internal space formed to have a vacuum by the attachment of the first and second substrates 31 and 32.

[0069] In addition, a getter is added to the internal space of the organic EL display, and serves to adsorb moisture and oxygen.

[0070] At this time, a getter made of barium with high oxidizing properties can be used.

[0071] FIG. 3 is a cross-sectional view illustrating an adhesive type organic EL display in accordance with a second embodiment of the present invention.

[0072] As shown in Fig. 3, the organic EL display of the second embodiment comprises a first substrate 31 having a p-Si thin transistor 39 formed thereon, and a second substrate 32 which has an organic EL element formed thereon, and is bonded to the first substrate 31.

[0073] An electrode of the thin transistor of the first substrate 31 is electrically connected with an electrode of the organic EL element of the second substrate 32.

[0074] The second substrate 32 has an assistant electrode 35, a first electrode 36 acting as an anode, at least two partition walls 33, an insulation film 34, an organic light emitting layer 37, and a second electrode 38 acting

as a cathode, formed thereon.

[0075] The at least two partition walls 33 are formed in a non-light emitting region of the second substrate 32, in which the island-shaped assistant electrode 35, and the first electrode 36 are formed below each partition wall 33.

[0076] The insulation layer 34 is formed to cover a portion of each partition wall 33.

[0077] Here, the insulation layer 34 covering the portion of one partition wall 33 is symmetrical to the insulation layer covering the portion of the other partition wall 33 adjacent to the one partition wall 33.

[0078] In other words, the insulation layer 34 is formed on sides of adjacent partition walls 33 in which the sides face each other, and the organic light emitting layer 37 is not formed between the adjacent partition walls 33.

[0079] A method for manufacturing the organic EL display of the second embodiment will be described as follows.

[0080] FIGs. 5A to 5D are cross-sectional views for illustrating steps of the method for manufacturing the adhesive type organic EL display in accordance with the first embodiment.

[0081] First, as shown in FIG. 5A, a first electrode 36 is formed on a second substrate 32, and an island-shaped assistant electrode 35 is formed on a non-light emitting region of the first electrode 36.

[0082] Here, the assistant electrode 35 can be composed of a conductive material, and is preferably composed of Al, Mo, an AnNd alloy, Cr, Cu, and the like.

[0083] In addition, the first electrode 36 acts as an anode, and is preferably composed of ITO or IZO.

[0084] Then, as shown in FIG. 5B, partition walls 33 are formed on the assistant electrode 35.

[0085] Next, as shown in FIG. 5C, an insulation layer 34 is formed to cover a portion of each partition wall 33.

[0086] Here, the insulation layer 34 is formed on sides of adjacent partition walls 33, which face each other.

[0087] In addition, as shown in FIG. 5D, an organic light emitting layer 37 is formed on the first electrode 36 of the light emitting region, and a second electrode 38 acting as a cathode is formed over the entire surface of the second substrate 32 including the organic light emitting layer 37.

[0088] Then, the first substrate 31 having the thin transistor is attached to the second substrate 32 having the organic EL element such that the second electrode 38 is electrically connected with the thin transistor of the first substrate 31, thereby completing the manufacture of the organic EL display.

[0089] As apparent from the above description, according to the present invention, since the organic EL display does not employ a spacer, it is possible to secure an aperture ratio, simplify the manufacturing process, enhance the reliability of the product, and improve optical efficiency.

[0090] It will be apparent to those skilled in the art that various modifications and variations can be made in the

present invention without departing from the spirit or scope of the inventions. Thus, it is intended that the present invention covers the modifications and variations of this invention provided they come within the scope of the appended claims and their equivalents.

Claims

1. An organic EL display, comprising a first substrate having a thin transistor formed thereon, and a second substrate having an organic EL element formed thereon, the thin transistor of the first substrate being electrically connected with the organic EL element of the second substrate, the organic EL display further comprising:
 - at least two partition walls formed in a non-light emitting region of the second substrate;
 - an insulation layer formed to cover a portion of each partition wall; and
 - a second electrode formed on the partition walls, and electrically connected to the thin transistor of the first substrate.
2. The organic EL display according to claim 1, wherein each of the partition walls has a structure of substrate/assistant electrode/first electrode or a structure of substrate/first electrode/assistant electrode stacked therebelow.
3. The organic EL display according to claim 2, wherein the first electrode is an anode, and the second electrode is a cathode.
4. The organic EL display according to claim 2, wherein the assistant electrode comprises at least one of Al, Mo, an AnNd alloy, Cr and Cu, and the first electrode comprises at least one of ITO and IZO.
5. The organic EL display according to claim 1, wherein the non-light emitting region has a structure of substrate/assistant electrode/first electrode/organic light emitting layer/second layer or a structure of substrate/first electrode/second electrode stacked between the partition walls.
6. The organic EL display according to claim 1, wherein each of the partition walls is a structure wherein a lower surface thereof is narrower than an upper surface thereof to be formed with the second electrode.
7. The organic EL display according to claim 1, wherein each of the partition walls comprises a first section having a lower surface thereof wider than an upper surface thereof to be formed with the second electrode, and a second section being formed on the upper surface of the first section, and wider than the

lower surface of the first section.

8. The organic EL display according to claim 1, wherein the insulation layer covering the portion of one partition wall is symmetrical to the insulation layer covering the portion of the other partition wall adjacent to the one partition wall.

9. The organic EL display according to claim 1, wherein the insulation layer comprises at least one of photosensitive polyimide, polyacryl, and novolac-based organic insulation layers.

10. An organic EL display, comprising a first substrate having a thin transistor formed thereon, and a second substrate having an organic EL element formed thereon, the thin transistor of the first substrate being electrically connected with the organic EL element of the second substrate, the organic EL display further comprising:

a light emitting region, and a non-light emitting region provided to the second substrate;

an assistant electrode formed on the second substrate of the non-light emitting region;

a first electrode formed over an entire surface of the second substrate including the assistant electrode;

at least two partition walls formed on the first electrode of the non-light emitting region;

an insulation layer to cover a portion of each partition wall;

a light emitting layer formed on the first electrode of the light emitting region; and

a second electrode formed over the entire surface of the second substrate including the light emitting layer, and electrically connected to the thin transistor of the first substrate.

11. The organic EL display according to claim 10, wherein the non-light emitting region has an organic light emitting layer, and the second electrode stacked on the first electrode between the partition walls.

12. An organic EL display, comprising a first substrate having a thin transistor formed thereon, and a second substrate having an organic EL element formed thereon, the thin transistor of the first substrate being electrically connected with the organic EL element of the second substrate, the organic EL display further comprising:

a light emitting region, and a non-light emitting region provided to the second substrate;

a first electrode formed on the second substrate;

an assistant electrode formed on the first electrode of the non-light emitting region;

partition walls formed on the assistant electrode;

an insulation layer to cover a portion of each partition wall;

a light emitting layer formed on the first electrode of the light emitting region; and

a second electrode formed over an entire surface of the second substrate including the light emitting layer, and electrically connected to the thin transistor of the first substrate.

13. The organic EL display according to claim 12, wherein the second electrode is formed on the first electrode between the partition walls in the non-light emitting region.

14. A method for manufacturing an organic EL display comprising a first substrate having a thin transistor formed thereon, and a second substrate having an organic EL element formed thereon, the method comprising the steps of:

forming an assistant electrode on a non-light emitting region of the second substrate;

forming a first electrode over an entire surface of the second substrate including an upper or lower portion of the assistant electrode;

forming partition walls on a region where the assistant electrode is formed;

forming an insulation layer to cover a portion of each partition wall;

forming a light emitting layer on the first electrode of the light emitting region; and

forming a second electrode over the entire surface of the second substrate including the light emitting layer; and

electrically connecting the second electrode with the thin transistor of the first substrate.

15. The method according to claim 14, wherein, when forming the first electrode on the assistant electrode, the insulation layer is formed on opposite sides of adjacent partition walls in which the opposite sides do not face each other, and the organic light emitting layer is formed between the sides of the adjacent partition walls in which the sides face each other.

16. The method according to claim 14, wherein, when forming the first electrode under the assistant electrode, the insulation layer is formed on sides of adjacent partition walls facing each other, and the organic light emitting layer is not formed between the adjacent partition walls.

17. The method according to claim 14, wherein, when forming the first electrode on the assistant electrode, the insulation layer is formed on opposite sides of adjacent partition walls in which the opposite sides do not face each other, and the organic light emitting layer is formed between the sides of the adjacent partition walls in which the sides face each other.

18. The method according to claim 14, wherein, when forming the first electrode under the assistant electrode, the insulation layer is formed on sides of adjacent partition walls facing each other, and the organic light emitting layer is not formed between the adjacent partition walls.

19. The method according to claim 14, wherein, when forming the first electrode on the assistant electrode, the insulation layer is formed on opposite sides of adjacent partition walls in which the opposite sides do not face each other, and the organic light emitting layer is formed between the sides of the adjacent partition walls in which the sides face each other.

20. The method according to claim 14, wherein, when forming the first electrode under the assistant electrode, the insulation layer is formed on sides of adjacent partition walls facing each other, and the organic light emitting layer is not formed between the adjacent partition walls.

21. The method according to claim 14, wherein, when forming the first electrode on the assistant electrode, the insulation layer is formed on opposite sides of adjacent partition walls in which the opposite sides do not face each other, and the organic light emitting layer is formed between the sides of the adjacent partition walls in which the sides face each other.

22. The method according to claim 14, wherein, when forming the first electrode under the assistant electrode, the insulation layer is formed on sides of adjacent partition walls facing each other, and the organic light emitting layer is not formed between the adjacent partition walls.

23. The method according to claim 14, wherein, when forming the first electrode on the assistant electrode, the insulation layer is formed on opposite sides of adjacent partition walls in which the opposite sides do not face each other, and the organic light emitting layer is formed between the sides of the adjacent partition walls in which the sides face each other.

24. The method according to claim 14, wherein, when forming the first electrode under the assistant electrode, the insulation layer is formed on sides of adjacent partition walls facing each other, and the organic light emitting layer is not formed between the adjacent partition walls.

25. The method according to claim 14, wherein, when forming the first electrode on the assistant electrode, the insulation layer is formed on opposite sides of adjacent partition walls in which the opposite sides do not face each other, and the organic light emitting layer is formed between the sides of the adjacent partition walls in which the sides face each other.

26. The method according to claim 14, wherein, when forming the first electrode under the assistant electrode, the insulation layer is formed on sides of adjacent partition walls facing each other, and the organic light emitting layer is not formed between the adjacent partition walls.

27. The method according to claim 14, wherein, when forming the first electrode on the assistant electrode, the insulation layer is formed on opposite sides of adjacent partition walls in which the opposite sides do not face each other, and the organic light emitting layer is formed between the sides of the adjacent partition walls in which the sides face each other.

28. The method according to claim 14, wherein, when forming the first electrode under the assistant electrode, the insulation layer is formed on sides of adjacent partition walls facing each other, and the organic light emitting layer is not formed between the adjacent partition walls.

29. The method according to claim 14, wherein, when forming the first electrode on the assistant electrode, the insulation layer is formed on opposite sides of adjacent partition walls in which the opposite sides do not face each other, and the organic light emitting layer is formed between the sides of the adjacent partition walls in which the sides face each other.

30. The method according to claim 14, wherein, when forming the first electrode under the assistant electrode, the insulation layer is formed on sides of adjacent partition walls facing each other, and the organic light emitting layer is not formed between the adjacent partition walls.

FIG. 1
Related Art

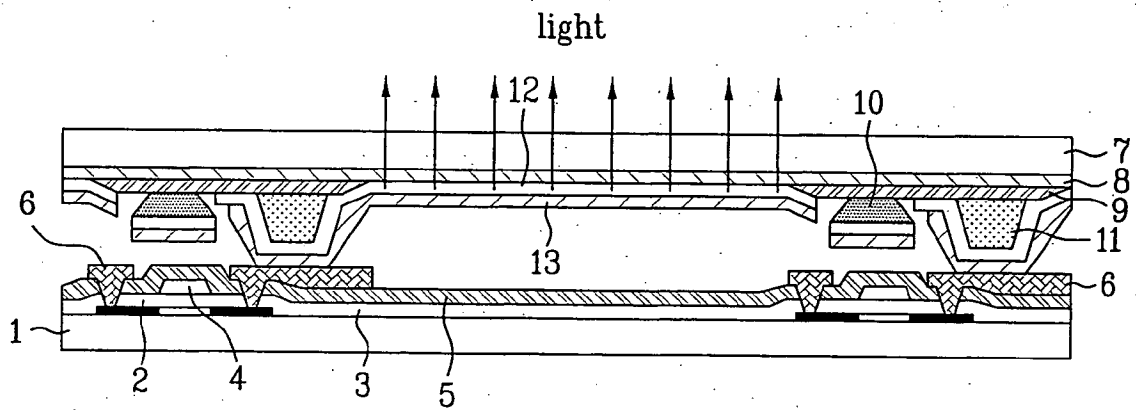


FIG. 2

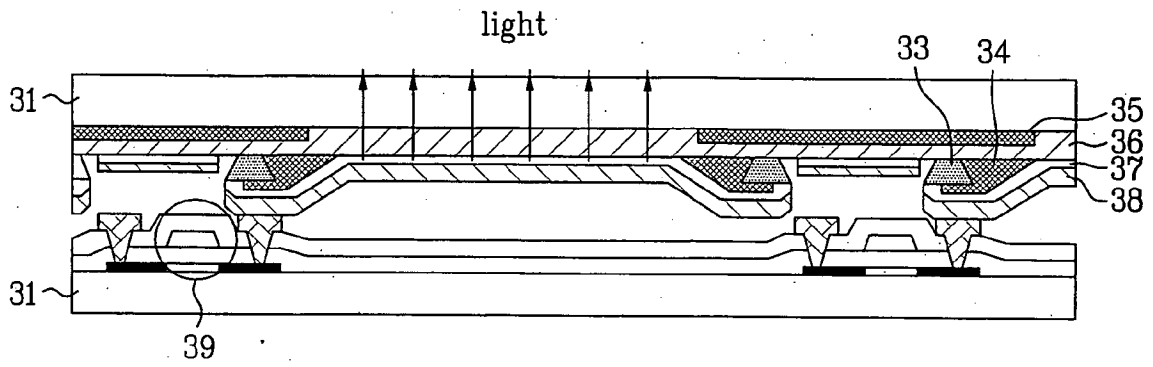


FIG. 3

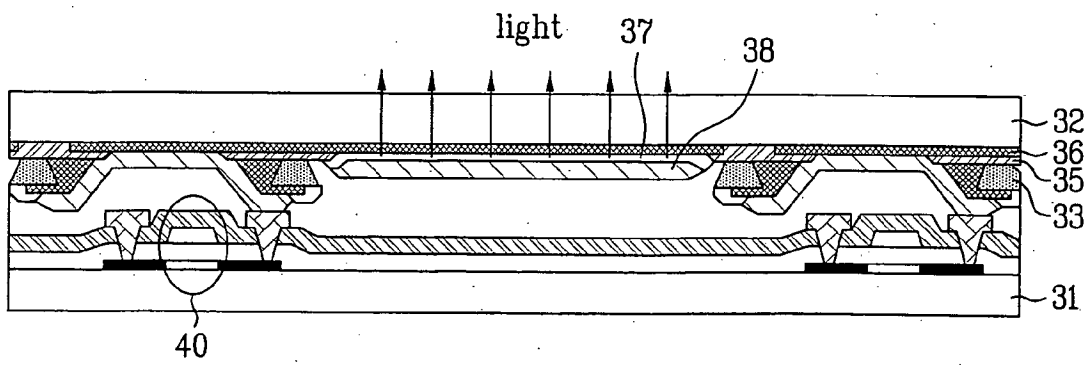


FIG. 4A

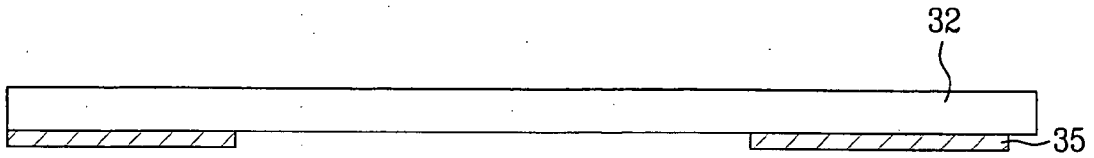


FIG. 4B

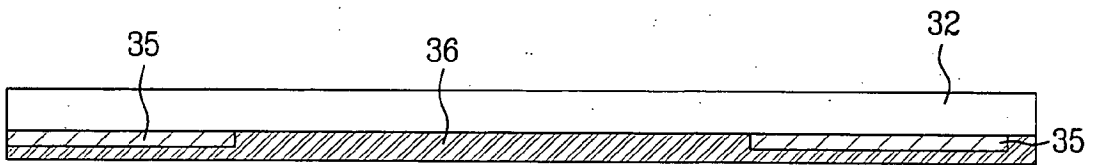


FIG. 4C

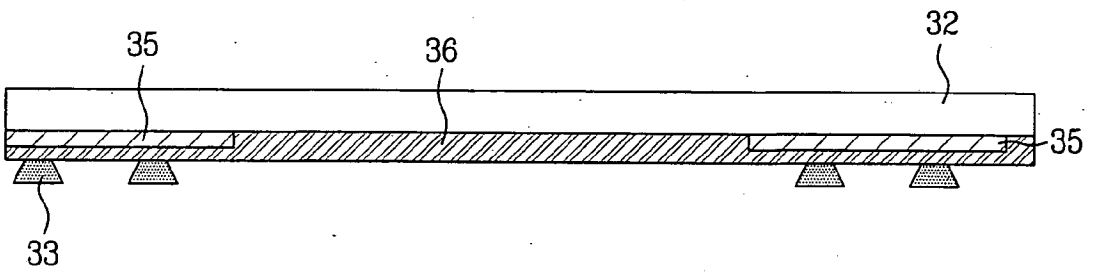


FIG. 4D

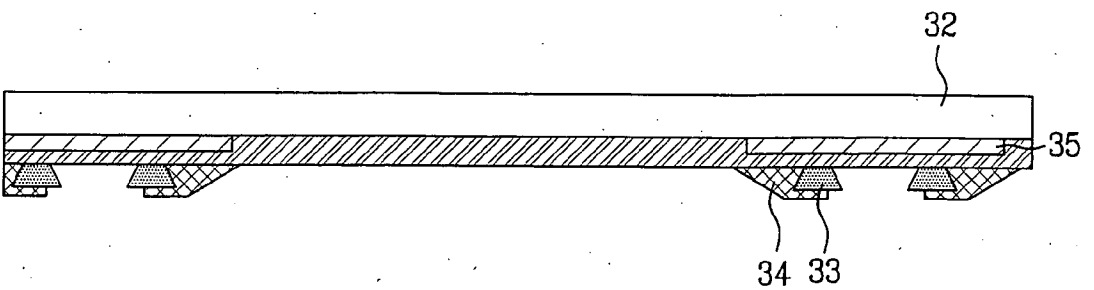


FIG. 4E

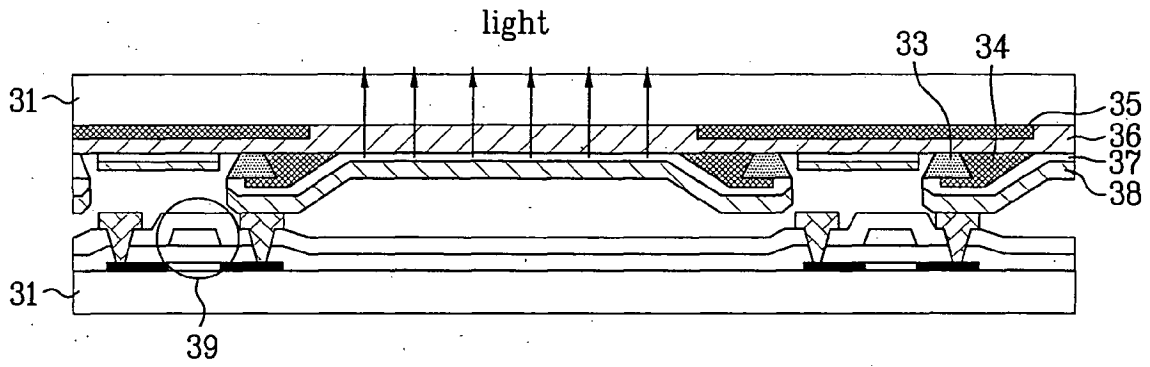


FIG. 5A

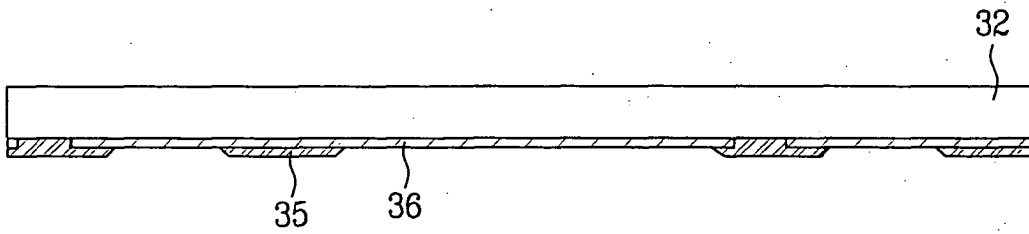


FIG. 5B

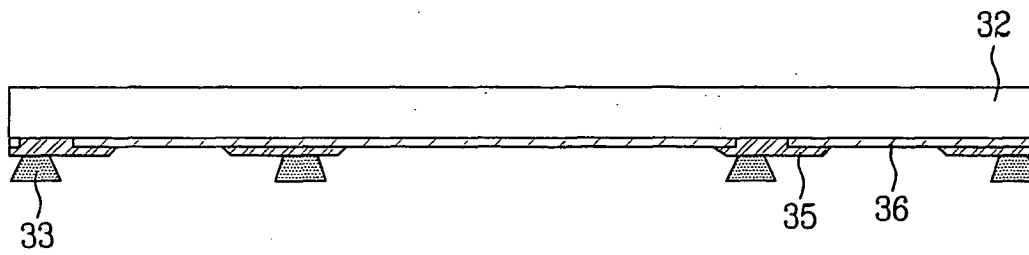


FIG. 5C

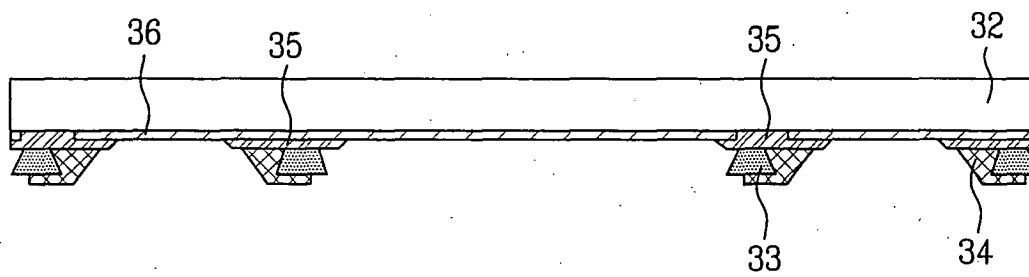


FIG. 5D

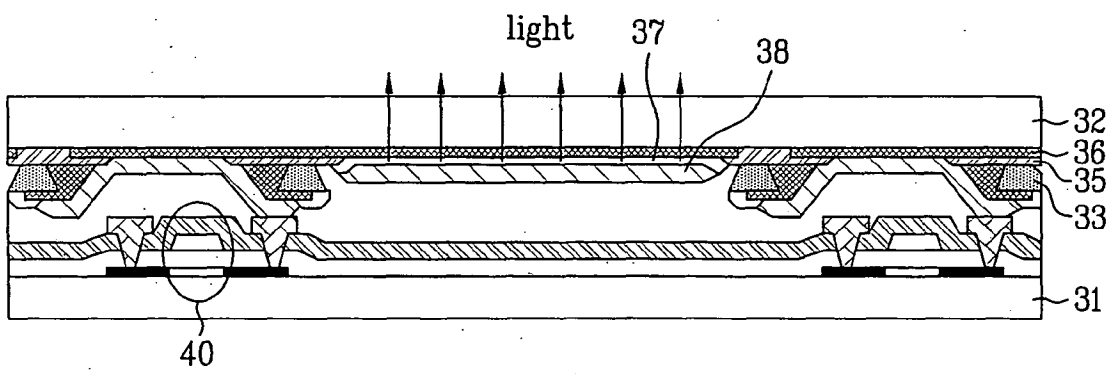


FIG. 6A

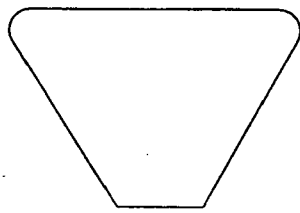
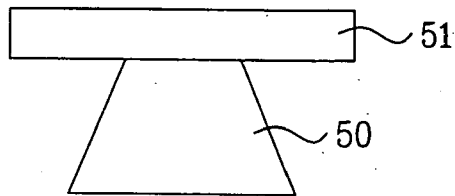


FIG. 6B



专利名称(译)	有机电致发光显示器及其制造方法		
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申请(专利权)人(译)	LG电子株式会社.		
当前申请(专利权)人(译)	LG DISPLAY CO. , LTD.		
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外部链接	Espacenet		

摘要(译)

公开了一种粘合型有机EL显示器及其制造方法。有机EL显示器包括：第一基板，其上形成有薄晶体管；以及第二基板，其上形成有有机EL元件。有机EL显示器还包括形成在第二基板的非发光区域中的至少两个分隔壁，形成为覆盖每个分隔壁的一部分的绝缘层，以及形成在分隔壁上的第二电极，并且电连接到第一衬底的薄晶体管。

FIG. 2

